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ASE news

ASE Hosts Third-Annual Tech Forum on Semiconductor Packaging and Test

Technology forum brings together leading semiconductor manufacturing experts to discuss trends, issues, and new technologies

Santa Clara, Calif., June 3, 2002 - Advanced Semiconductor Engineering, Inc. (ASE) (NYSE: ASX), one of the world's largest semiconductor IC packaging and test companies, will host its third annual Tech Forum in June. This year, the one-day symposium will be held in Austin, Texas, June 13; Santa Clara (Silicon Valley), Calif., June 18; and Ottawa, Ontario, Canada, June 20.

The ASE Tech Forum is designed to provide chip makers with the latest trends in semiconductor back-end assembly and test technology, focusing on maximizing chip performance and minimizing time-to-market.

"This year's ASE Tech Forum comes at a critical time for our partners in the semiconductor industry as we emerge from one of the worst economic downturns," said Dr. Tien Wu, president, ASE Americas and Europe. "The ASE Tech Forum will pull together some of the brightest minds in the industry to discuss and present next-generation semiconductor packaging and test solutions."

The ASE Tech Forum 2002 highlights include:

- Technical discussions by ASE's senior research engineering team regarding: flip-chip bumping and assembly, wafer-level packaging, system-in-package, and design-to-test techniques for high-speed applications at all three Tech Forum symposia.
- Presentations by C. Scott Kulicke, chairman and CEO of Kulicke and Soffa Industries Inc. (Nasdaq: KLIC), the world's leading supplier of semiconductor interconnect equipment, materials and technology; and Dr. Genda Hu, vice president of corporate marketing at Taiwan Semiconductor Manufacturing Company Ltd (NYSE: TSM), the world's largest dedicated semiconductor foundry, at Tech Forum Silicon Valley.
- Presentation by Jan Vardaman, president of TechSearch International, Inc., a leading consulting company in advanced packaging (www.techsearchinc.com) at Tech Forum Austin.

- Presentations by ASE's ATE (automatic test equipment) partners; Agilent, Schlumberger, and Teradyne, during technical breakout sessions at Tech Forums Austin and Silicon Valley.
- A mini-exhibition by ASE's partners at Tech Forums Austin and Silicon Valley.

To register for the ASE Tech Forum 2002 or to find more information about the event, please visit the event website at <http://www.asetechforum.com>

About ASE Inc.

ASE Inc. (TAIEX: 2311, NYSE: ASX) is one of the world's largest independent providers of semiconductor packaging services and, together with its subsidiary ASE Test Limited (Nasdaq:ASTSF), the world's largest independent providers of semiconductor testing services, including front-end engineering testing, wafer probing and final testing services. The Company's international customer base of more than 200 blue-chip customers includes such leading names as Advanced Micro Devices, Inc., Altera Corporation, Cirrus Logic Inc., Conexant Systems, Inc., LSI Logic Corporation, and Qualcomm Inc. With advanced-process technological capabilities and a global presence spanning Taiwan, Korea, Hong Kong, Singapore, Malaysia and the United States, ASE Inc. has established a reputation for reliable, high quality products and services. For more information, visit the website, <http://www.aseglobal.com>

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